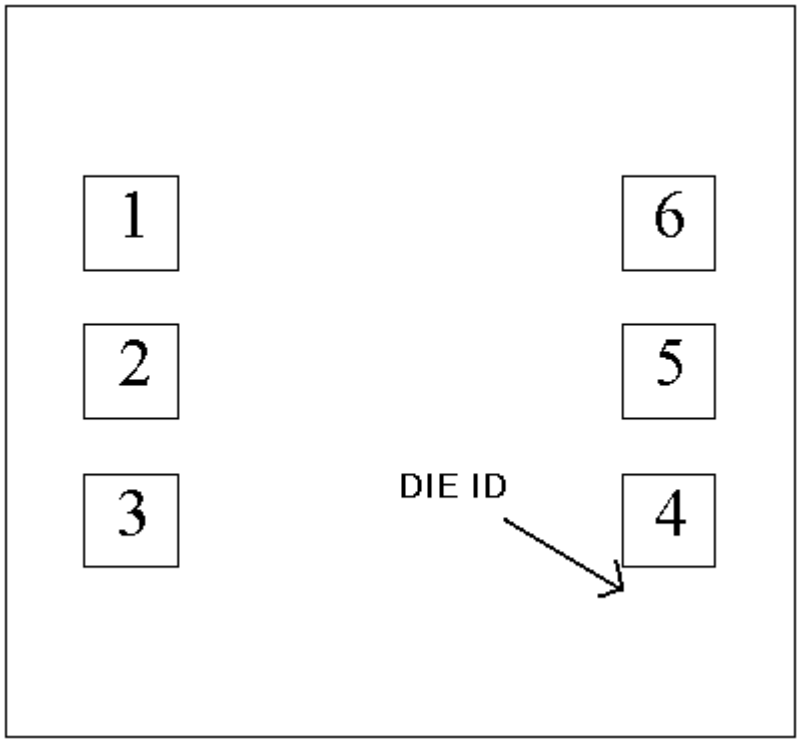
DS90LV012A MDC MWC
3V LVDS SINGLE CMOS DIFFERENTIAL LINE RECEIVER

January 29,2007

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	DS90LV012AA	Bond Pad Opening Size (min)	102µm x 102µm
Die Step	A	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	864µm x 800µm 34.0mils x 31.5mils	Back Side Connection	GND
Thickness	254µm Nominal		
Min Pitch	161.5µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
VDD	1	-294	162	102	x	102
GND	2	-294	0	102	x	102
TTL OUT	3	-294	-163	102	x	102
IN-	4	294	-163	102	x	102
GND	5	294	0	102	x	102
IN+	6	294	162	102	x	102

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The Sight & Sound of Information

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